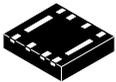


MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

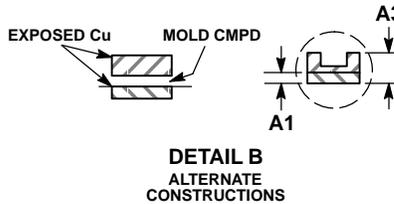
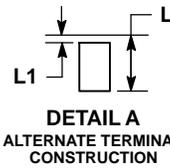
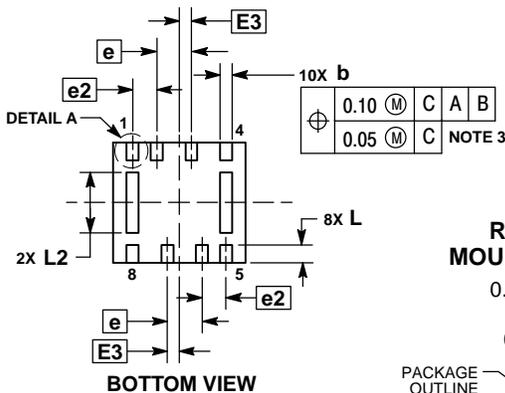
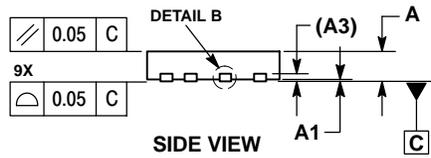
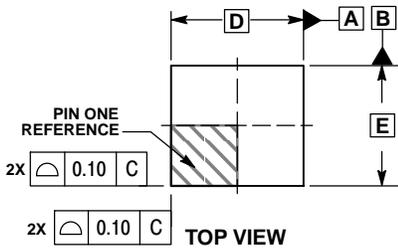
ON Semiconductor®



SCALE 4:1

UDFN8 2.2x2, 0.575P CASE 506CV ISSUE A

DATE 21 JUL 2015



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSIONS b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.25 MM FROM TERMINAL TIP.

MILLIMETERS		
DIM	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.127	REF
b	0.15	0.25
D	2.20	BSC
E	2.00	BSC
E3	0.20	BSC
e	0.575	BSC
e2	0.40	BSC
L	0.25	0.35
L1	0.05	0.15
L2	0.95	1.05

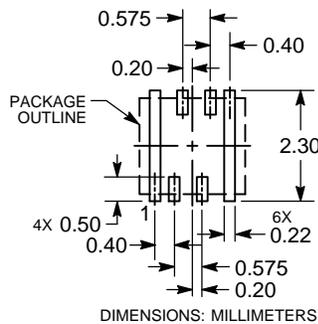
GENERIC MARKING DIAGRAM*



XX = Specific Device Code
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present.

RECOMMENDED MOUNTING FOOTPRINT



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NEW STANDARD:		
DESCRIPTION:	UDFN8 2.2X2, 0.575P	PAGE 1 OF 2

